



## Materials Declaration Form


<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>31-01-2018</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST7FLITES2Y0M6	P6Q7*819XXX3	B	9998	31-01-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	150.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6x3.8	16		
Comment	Package : Q7 SO 16 .15 TO JEDEC MS-012 0016020			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P6Q7*819XXX3				5000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.378	mg	supplier	die	Silicon (Si)	7440-21-3		7.223	mg	978992	48153
				supplier	metallization	Copper (Cu)	7440-50-8		0.126	mg	17078	840
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	678	33
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	813	40
				supplier	Passivation	Silicon Oxide	7631-86-9		0.018	mg	2440	120
Leadframe	Copper & its alloys	67.564	mg	supplier	alloy	Copper (Cu)	7440-50-8		65.584	mg	970694	437227
				supplier	alloy	Iron (Fe)	7439-89-6		1.543	mg	22838	10287
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.093	mg	1376	620
				supplier	alloy	Zinc (Zn)	7440-66-6		0.081	mg	1199	540
				supplier	metallization	Silver (Ag)	7440-22-4		0.263	mg	3893	1753
Bonding wires	Precious metals	0.277	mg	supplier	wire	Gold (Au)	7440-57-5		0.277	mg	1000000	1847
Encapsulation	M-011 Other inorganic materials	71.951	mg	supplier	mold compound	Silica, vitreous	60676-86-0		62.525	mg	868994	416833
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		5.756	mg	79999	38373
				supplier	mold compound	Phenol Resin	26834-02-6		2.878	mg	39999	19187
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.432	mg	6004	2880
				supplier	mold compound	Carbon black	1333-86-4		0.360	mg	5003	2400
connections coating	Solder	2.830	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.830	mg	1000000	18867